IN THE CLAIMS:

Please cancel Claims 1-28, 31-40, and 43-48 without prejudice or disclaimer of the subject matter presented therein.

Please amend Claims 29, 30, 41, 42, and 49, and add new Claim 50, to read as shown below.

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1. - 28. (Cancelled).

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29. (Currently Amended) An ~~electronic~~ electron-emitting device manufacturing method ~~characterized by~~ comprising:

~~the~~ a gas removal step of removing a gas dissolved in a liquid containing a formation material of ~~a member constituting an electronic device~~ an electroconductive film in which an electron-emitting area is to be formed;

a temperature adjusting step of adjusting a temperature of the liquid from which the gas is removed; and

~~the~~ a droplet discharge step of discharging droplets of which the temperature is adjusted by droplet discharge means in an ink jet manner while controlling relative positions of the droplet discharge means for discharging droplets of the liquid and a substrate on which the ~~electronic device~~ electroconductive film in which the electron-emitting area is to be formed is formed, thereby applying the droplets to a predetermined position on the substrate.

30. (Currently Amended) An ~~electronic~~ electron-emitting device manufacturing method according to claim 29, ~~characterized in that~~ wherein the gas removal step comprises controlling a concentration of the gas dissolved in the liquid so as to be kept at a default value.

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31. - 40. (Canceled)

41. (Currently Amended) An electron-emitting device manufacturing method according to claim 29, wherein, in the droplet discharge step, the droplet discharge means discharges the droplets of adjusted temperature in the ink jet manner onto a plurality of predetermined positions on the substrate, thereby applying the droplets to the predetermined positions on the substrate.

~~source substrate manufacturing method of manufacturing an electron source substrate having a plurality of pairs of element electrodes formed on a substrate, conductive films each having an electron-emitting portion formed between each pair of element electrodes, and a voltage application terminal to each element electrode, characterized by comprising:~~

~~the gas removal step of removing a gas dissolved in a solution containing a metal element; and~~

~~the droplet discharge step of discharging droplets by droplet discharge means while controlling relative positions of the substrate and the droplet discharge means~~

~~for discharging droplets of the solution, thereby applying the droplets to a predetermined position on the substrate.~~

42. (Currently Amended) An ~~electron source substrate~~ electron-emitting device manufacturing method according to claim 41, ~~characterized in that~~ wherein the gas removal step comprises controlling a concentration of the gas dissolved in the ~~solution~~ liquid so as to be kept at a default value.

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43. - 48. (Canceled)

49. (Currently Amended) An image forming apparatus manufacturing method of manufacturing an image forming apparatus having an electron source substrate in which a plurality of electron-emitting devices are disposed and a light-emitting member which emits light upon irradiation of electrons from the electron source substrate, ~~characterized in that the~~ wherein each electron-emitting device ~~source substrate~~ is manufactured by the method ~~defined in~~ according to claim 41 ~~or 45~~.

50. (New) An image forming apparatus manufacturing method according to claim 49, wherein, in the gas removal step, a concentration of the gas dissolved in the liquid is controlled to be maintained at a predetermined value.